Switching Transistor

PNP Silicon

Features

• These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector - Emitter Voltage	V_{CEO}	-40	Vdc
Collector - Base Voltage	V_{CBO}	-40	Vdc
Emitter – Base Voltage	V_{EBO}	-5.0	Vdc
Collector Current - Continuous	I _C	-600	mAdc
Collector Current - Peak	I _{CM}	-900	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) @T _A = 25°C Derate above 25°C	P _D	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate, (Note 2) @T _A = 25°C Derate above 25°C	P _D	300 2.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T _J , T _{stg}	-55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

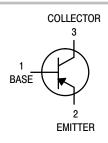
*Transient pulses must not cause the junction temperature to be exceeded.

- 1. FR-5 = $1.0 \times 0.75 \times 0.062$ in.
- 2. Alumina = 0.4 \times 0.3 \times 0.024 in. 99.5% alumina.



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SOT-23 (TO-236) CASE 318 STYLE 6

MARKING DIAGRAM



2T = Specific Device Code

M = Date Code*

= Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]
MMBT4403LT1G	SOT-23 (Pb-Free)	3000 Tape & Reel
MMBT4403LT3G	SOT-23 (Pb-Free)	10,000 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic			Min	Max	Unit
OFF CHARACTERISTICS			1	•	1
Collector - Emitter Breakdown Voltage	(Note 3) $(I_C = -1.0 \text{ mAdc}, I_B = 0)$	V _{(BR)CEO}	-40	-	Vdc
Collector - Base Breakdown Voltage	$(I_C = -0.1 \text{ mAdc}, I_E = 0)$	V _{(BR)CBO}	-40	-	Vdc
Emitter – Base Breakdown Voltage	$(I_E = -0.1 \text{ mAdc}, I_C = 0)$	V _{(BR)EBO}	-5.0	-	Vdc
Base Cutoff Current	$(V_{CE} = -35 \text{ Vdc}, V_{EB} = -0.4 \text{ Vdc})$	I _{BEV}	-	-0.1	μAdc
Collector Cutoff Current	$(V_{CE} = -35 \text{ Vdc}, V_{EB} = -0.4 \text{ Vdc})$	I _{CEX}	-	-0.1	μAdc
ON CHARACTERISTICS		•	•		
DC Current Gain (Note 3) (Note 3)	$ \begin{array}{l} (I_C = -0.1 \text{ mAdc, } V_{CE} = -1.0 \text{ Vdc}) \\ (I_C = -1.0 \text{ mAdc, } V_{CE} = -1.0 \text{ Vdc}) \\ (I_C = -10 \text{ mAdc, } V_{CE} = -1.0 \text{ Vdc}) \\ (I_C = -150 \text{ mAdc, } V_{CE} = -2.0 \text{ Vdc}) \\ (I_C = -500 \text{ mAdc, } V_{CE} = -2.0 \text{ Vdc}) \end{array} $	h _{FE}	30 60 100 100 20	- - - 300 -	_
Collector - Emitter Saturation Voltage (Note 3)	V _{CE(sat)}		-0.4 -0.75	Vdc
Base – Emitter Saturation Voltage (Note 3) $ (I_C = -150 \text{ mAdc}, \ I_B = -15 \text{ mAdc}) \\ (I_C = -500 \text{ mAdc}, \ I_B = -50 \text{ mAdc}) $		V _{BE(sat)}	-0.75 -	-0.95 -1.3	Vdc
SMALL-SIGNAL CHARACTERISTIC	s	•	•		
Current – Gain – Bandwidth Product (I _C = -20 mAdc, V _{CE} = -10 Vdc, f = 100 MHz)		f _T	200	-	MHz
Collector-Base Capacitance	(V _{CB} = -10 Vdc, I _E = 0, f = 1.0 MHz)	C _{cb}	_	8.5	pF
Emitter-Base Capacitance	$(V_{BE} = -0.5 \text{ Vdc}, I_C = 0, f = 1.0 \text{ MHz})$	C _{eb}	_	30	pF
Input Impedance ($I_C = -1.0 \text{ mAdc}$, $V_{CE} = -10 \text{ Vdc}$, $f = 1.0 \text{ kHz}$)		h _{ie}	1.5	15	kΩ
Voltage Feedback Ratio $(I_C = -1.0 \text{ mAdc}, V_{CE} = -10 \text{ Vdc}, f = 1.0 \text{ kHz})$		h _{re}	0.1	8.0	X 10 ⁻⁴
Small – Signal Current Gain (I _C = -1.0 mAdc, V _{CE} = -10 Vdc, f = 1.0 kHz)		h _{fe}	60	500	_
Output Admittance ($I_C = -1.0 \text{ mAdc}$, $V_{CE} = -10 \text{ Vdc}$, $f = 1.0 \text{ kHz}$)		h _{oe}	1.0	100	μMhos
SWITCHING CHARACTERISTICS					
Delay Time	(V _{CC} = -30 Vdc, V _{EB} = -2.0 Vdc,	t _d	-	15	
Rise Time	$I_C = -150 \text{ mAdc}, I_{B1} = -15 \text{ mAdc})$	t _r	-	20	ns
Storage Time	$(V_{CC} = -30 \text{ Vdc}, I_{C} = -150 \text{ mAdc},$	t _s	_	225	no
Fall Time	$I_{B1} = I_{B2} = -15 \text{ mAdc}$	t _f	-	30	- ns

^{3.} Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%.

SWITCHING TIME EQUIVALENT TEST CIRCUIT

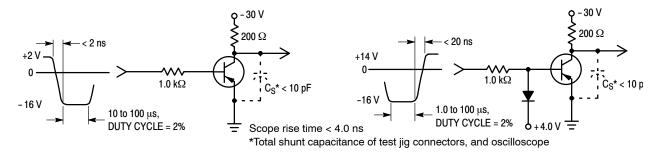
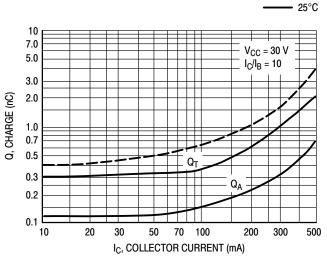


Figure 1. Turn-On Time

Figure 2. Turn-Off Time

TRANSIENT CHARACTERISTICS



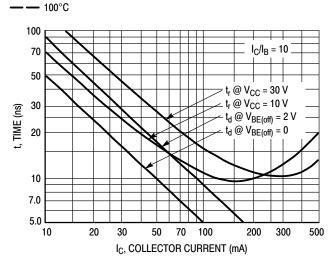
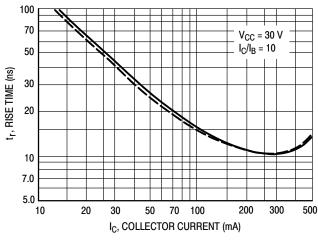


Figure 3. Charge Data

Figure 4. Turn-On Time



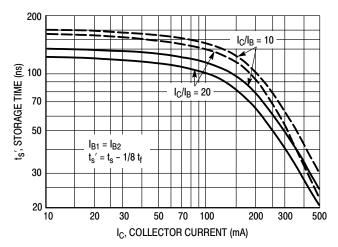
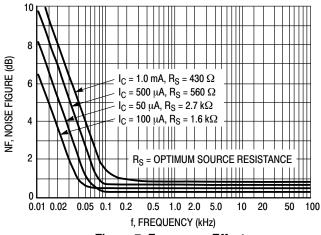


Figure 5. Rise Time

Figure 6. Storage Time

SMALL-SIGNAL CHARACTERISTICS NOISE FIGURE

 $V_{CE} = -10 \text{ Vdc}, T_A = 25^{\circ}\text{C}; Bandwidth} = 1.0 \text{ Hz}$



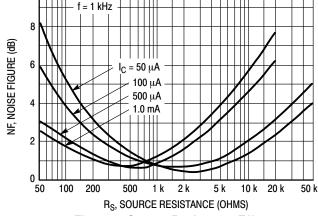


Figure 7. Frequency Effects

Figure 8. Source Resistance Effects

h PARAMETERS

$$V_{CE}$$
 = 10 Vdc, f = 1.0 kHz, T_A = 25°C

This group of graphs illustrates the relationship between h_{fe} and other "h" parameters for this series of transistors. To obtain these curves, a high-gain and a low-gain unit were selected from the MMBT4403LT1 lines, and the same units were used to develop the correspondingly numbered curves on each graph.

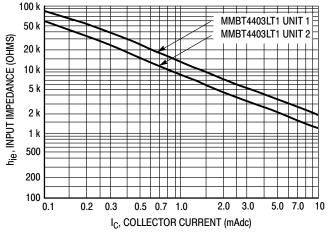


Figure 9. Input Impedance

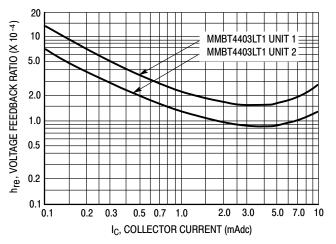


Figure 10. Voltage Feedback Ratio

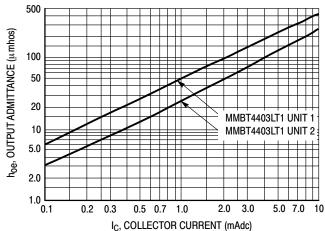


Figure 11. Output Admittance

STATIC CHARACTERISTICS

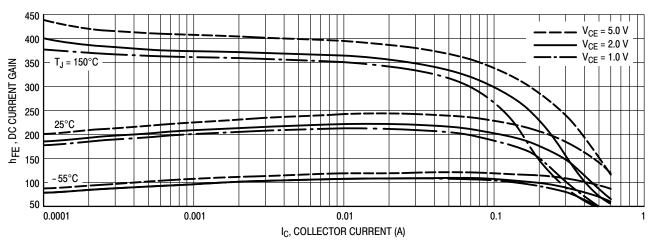


Figure 12. DC Current Gain

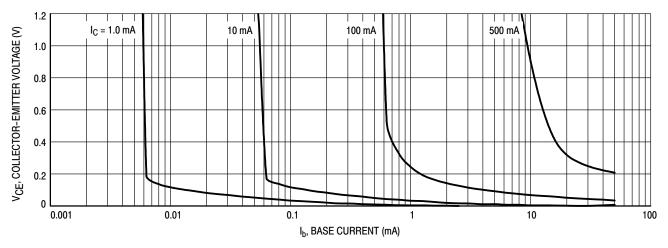


Figure 13. Collector Saturation Region

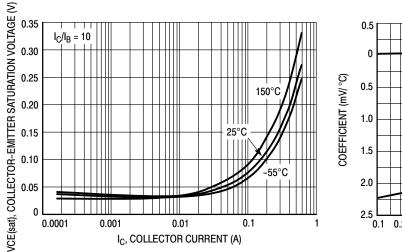


Figure 14. Collector-Emitter Saturation Voltage vs. Collector Current

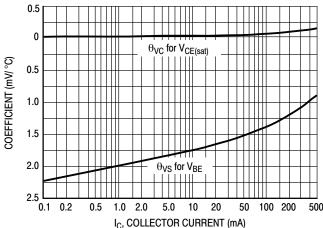


Figure 15. Temperature Coefficients

STATIC CHARACTERISTICS

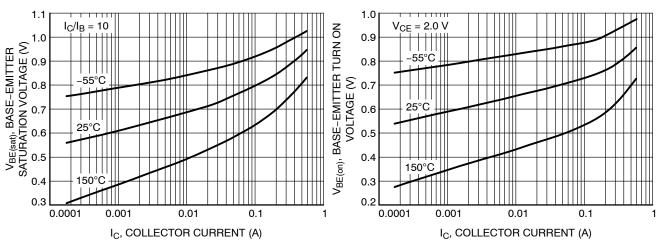


Figure 16. Base–Emitter Saturation Voltage vs.
Collector Current

Figure 17. Base–Emitter Turn On Voltage vs. Collector Current

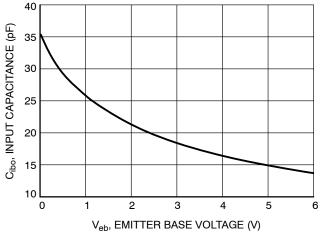


Figure 18. Input Capacitance vs. Emitter Base Voltage

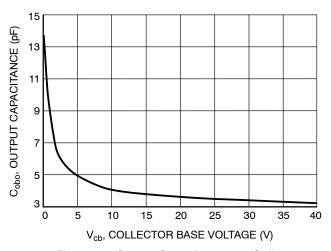


Figure 19. Output Capacitance vs. Collector Base Voltage

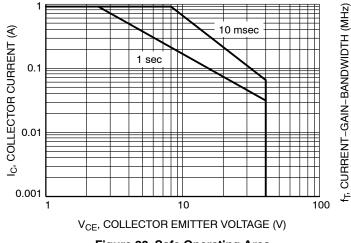


Figure 20. Safe Operating Area

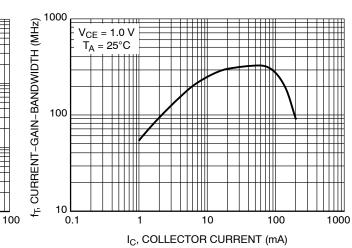
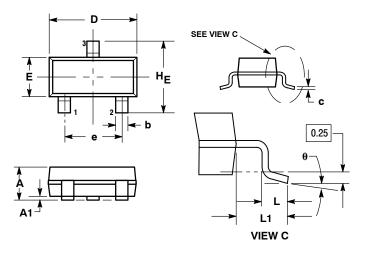


Figure 21. Current-Gain-Bandwidth Product

PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AN**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER

 - ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. MAXIMUM LEAD THICKNESS INCLUDES
 LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF
 - BASE MATERIAL. 4. 318-01 THRU -07 AND -09 OBSOLETE, NEW STANDARD 318-08.

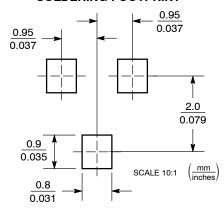
	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
С	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104

STYLE 6:

PIN 1. BASE **EMITTER** 2.

COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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